

COMSOL Conference 2015

Pankaj Priyadarshi
IIT Bombay, Mumbai



Content

- Introduction
- Governing Equation
- Thermoelectric Unicouple
- Results
- References



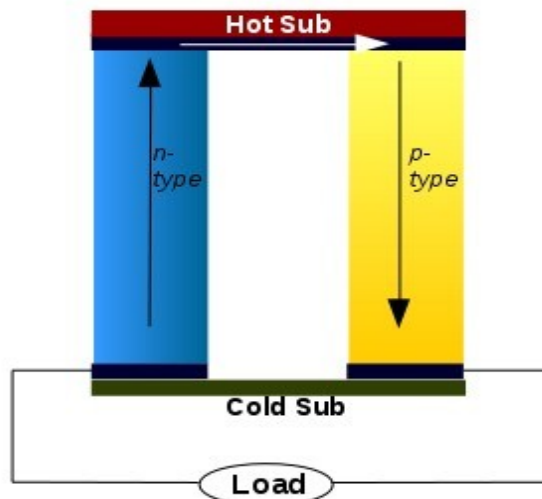
Introduction

- Energy Harvesting
- Thermoelectricity

Three Effects-

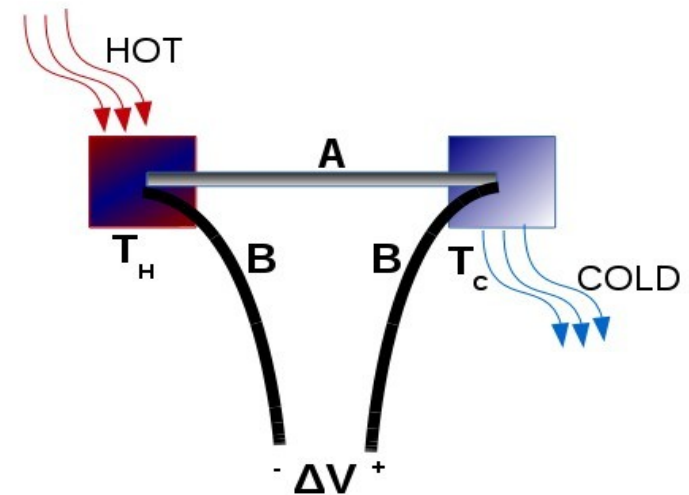
1.) Seebeck Effect

Open circuit voltage (*Averaging Seebeck coefficient*)



$$V_{OC} = \int_{T_C}^{T_H} \alpha(T) dT$$

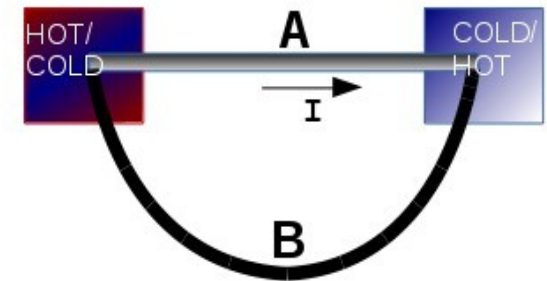
$$\alpha = \alpha_p - \alpha_n$$



Introduction

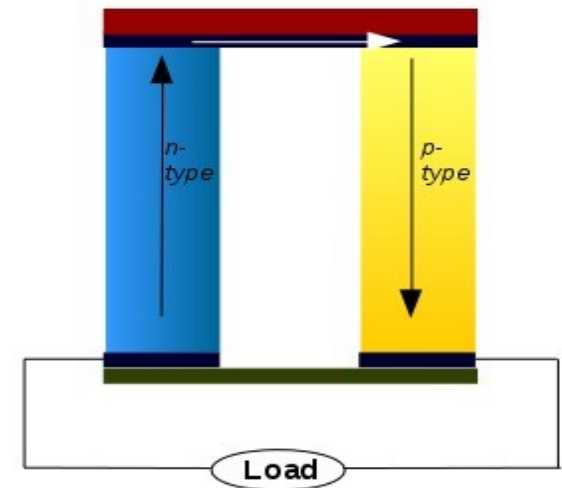
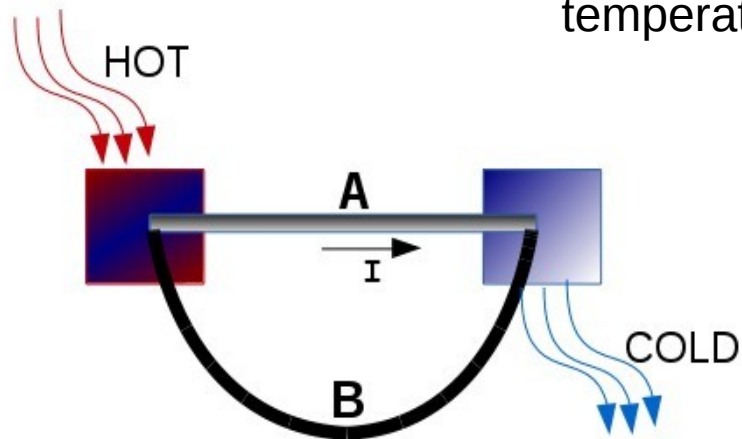
2.) Peltier Effect

$$Q = \alpha_{total} T_{H/C} I$$



3.) Thomson Effect

Heat is proportional to electric current and temperature difference.

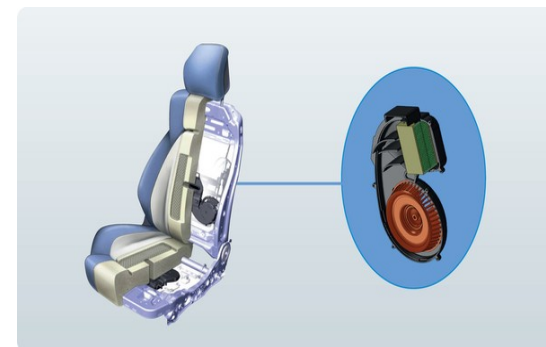
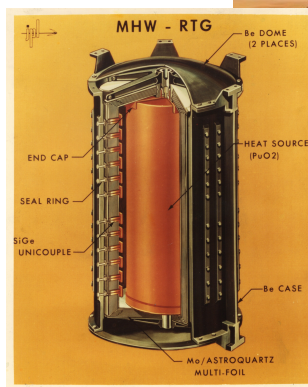
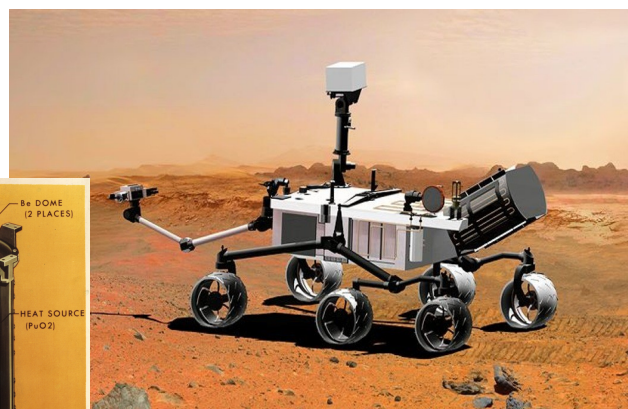
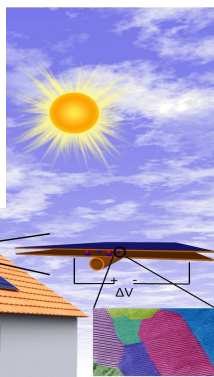
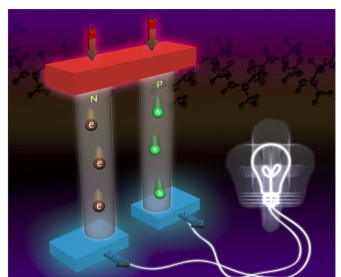
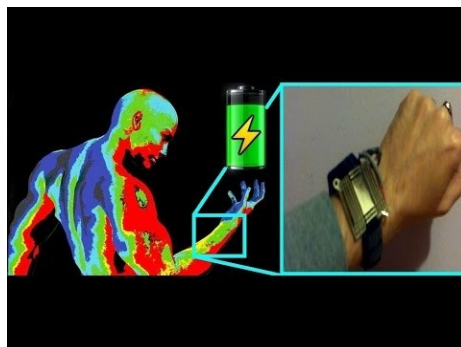


small enough to be neglected



Introduction

- Applications



Governing Equation

Used in COMSOL

$$\rho C_P \frac{\partial T}{\partial t} + \nabla \cdot (-\kappa \nabla T + \alpha T J) = Q$$

Steady state (including Joule heating)

$$\frac{T_H - T_C}{R_T} - \frac{I^2 R_E}{2} + \alpha I T_H = Q_H$$

$$\frac{T_H - T_C}{R_T} + \frac{I^2 R_E}{2} + \alpha I T_C = Q_C$$

Conduction heat flow

A thermoelectric effect node also adds :

$$J = -\sigma (\nabla V + \alpha \nabla T)$$



Governing Equation

Terminal Voltage

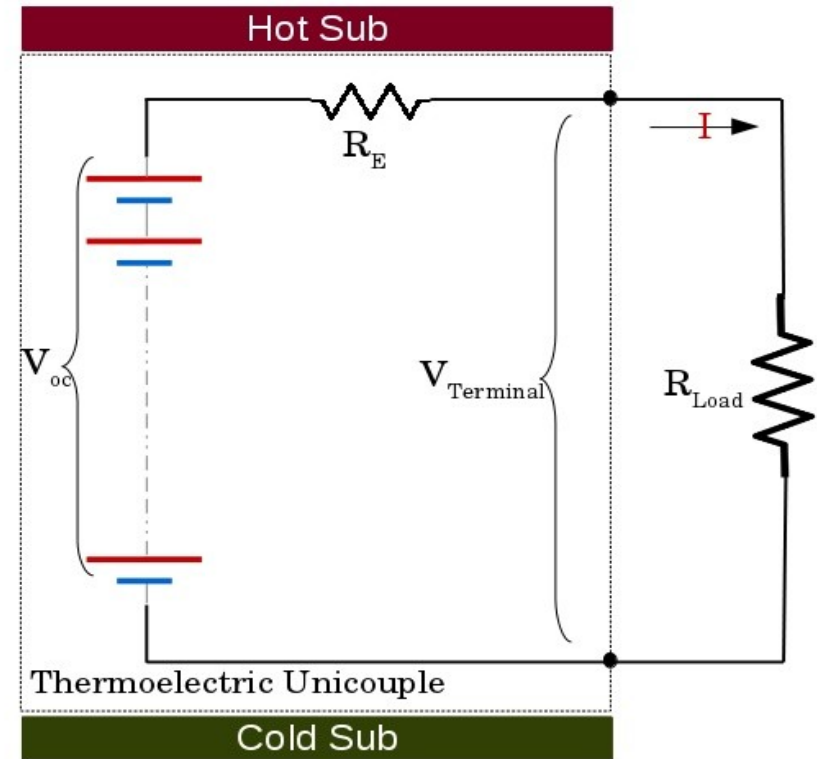
$$P = Q_H - Q_C = IV$$

$$= V_{OC} I - I^2 R_E$$

Emf generated due to Seebeck effect

Loss due to Joule heating

$$\Rightarrow V_{Terminal} = V_{OC} - IR_E$$



Governing Equation

- Geometry factor

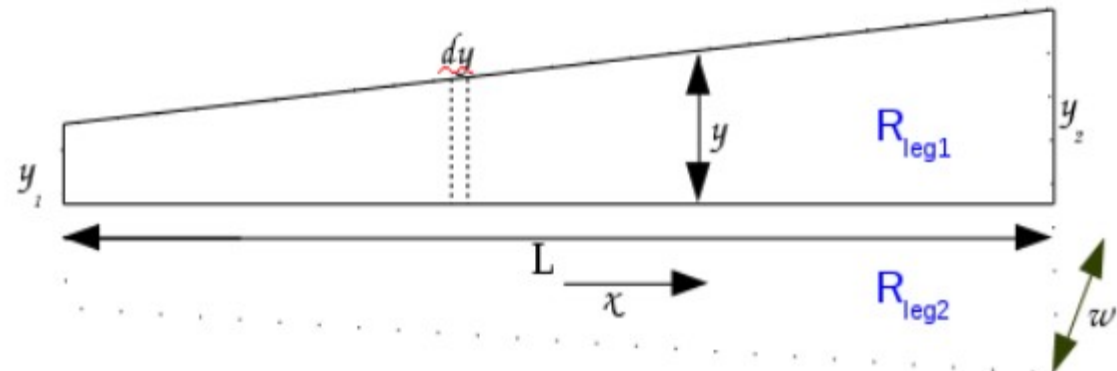
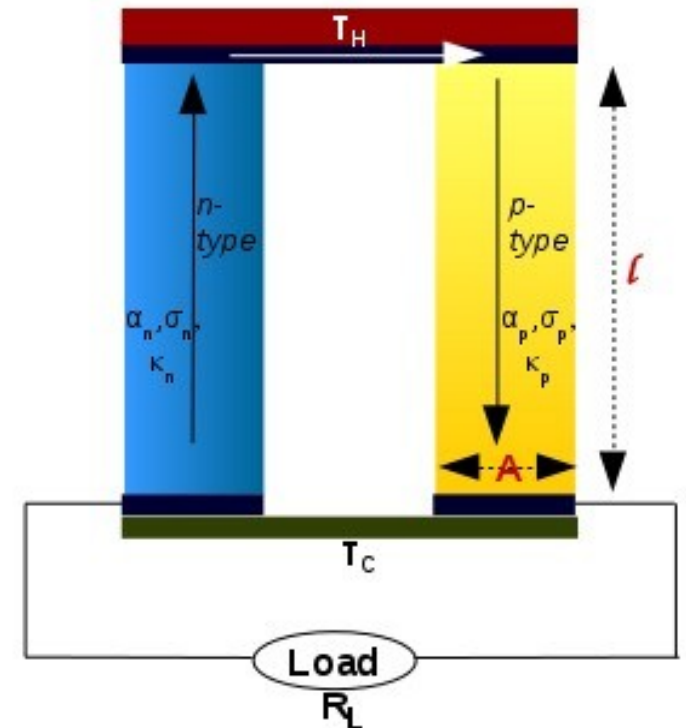
$$R_E = R_{E,p} + R_{E,n} = \frac{l}{\sigma_p A} + \frac{l}{\sigma_n A}$$

$$R_T = R_{T,p} || R_{T,n} = \frac{l}{\kappa_p A + \kappa_n A}$$

When structure varying along the length

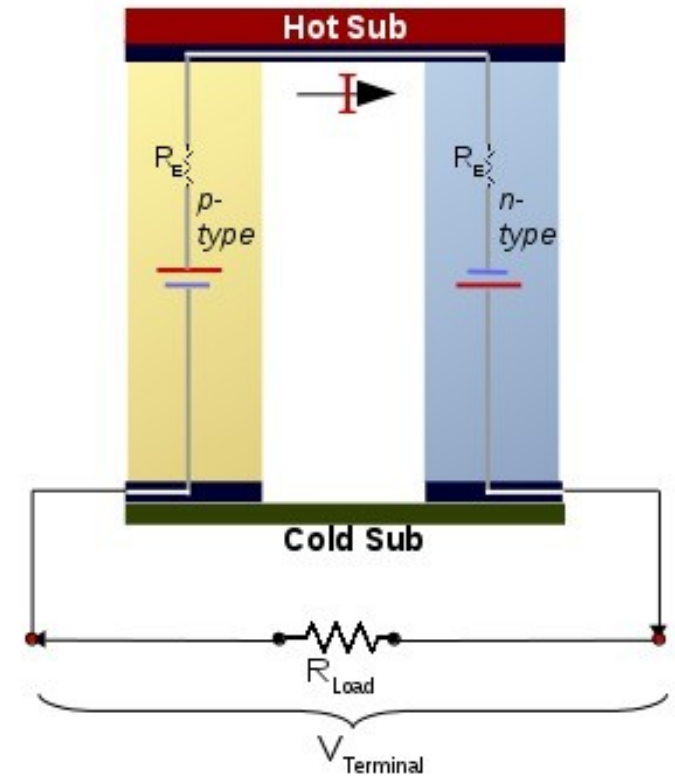
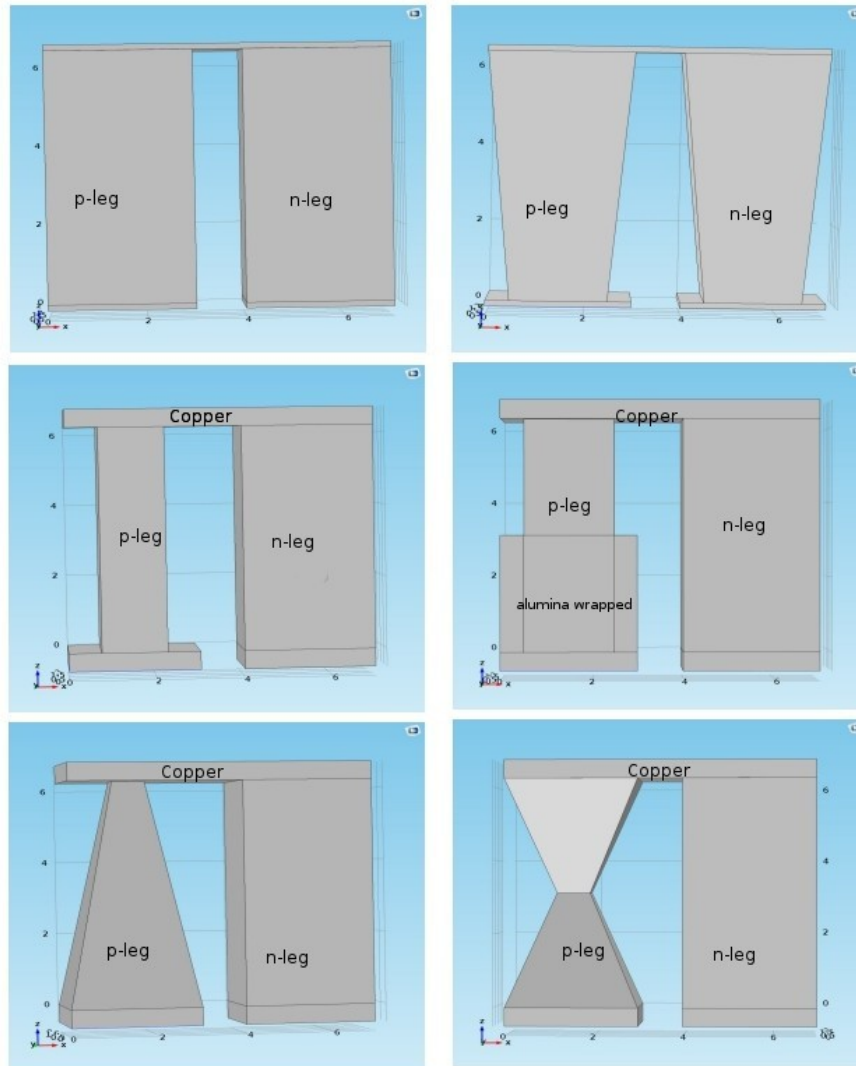
$$R_E = \int dR = \frac{1}{\sigma} \int \frac{dx}{wy}$$

$$K_T = \int dK = \kappa_{avg} \int \frac{wy}{dx}$$



Thermoelectric Unicouple

- Different shape & size of unicouple for simulation

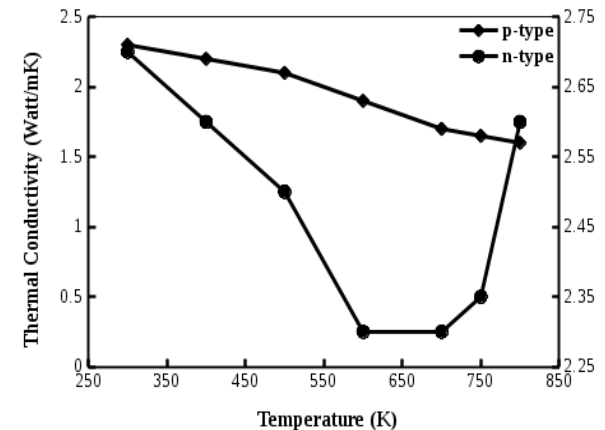
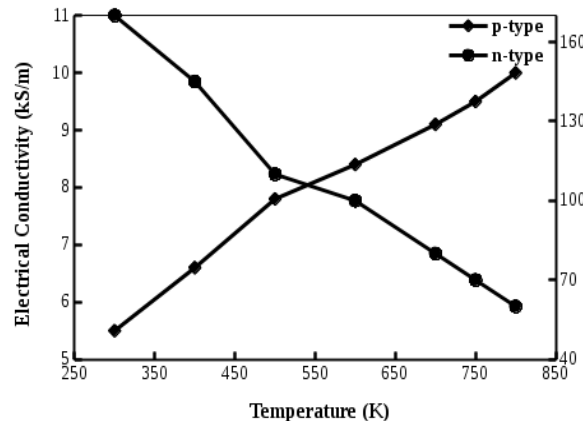
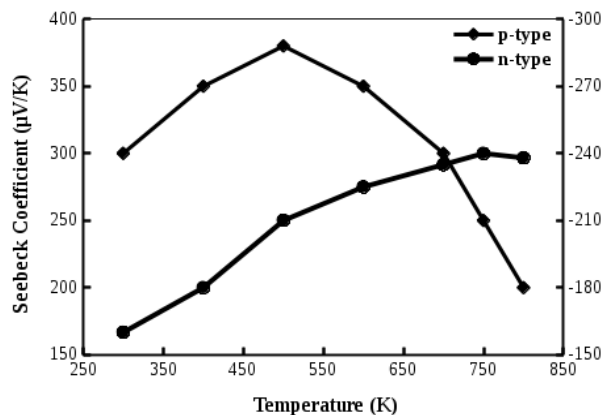


Dimension:- 6.22 x 2.98 x 2.215 mm³

Tapering factor:- 0.25 & 0.5

Thermoelectric Unicouple

- Temperature dependent material properties for Mg₂Si
- High Seebeck coefficient measured in Ga-doped samples
- Electrical conductivity slowly increases in the whole temperature range
- Operate under large temperature ranges (250-850 K)
- Electronic thermal conductivity is much lower than the lattice



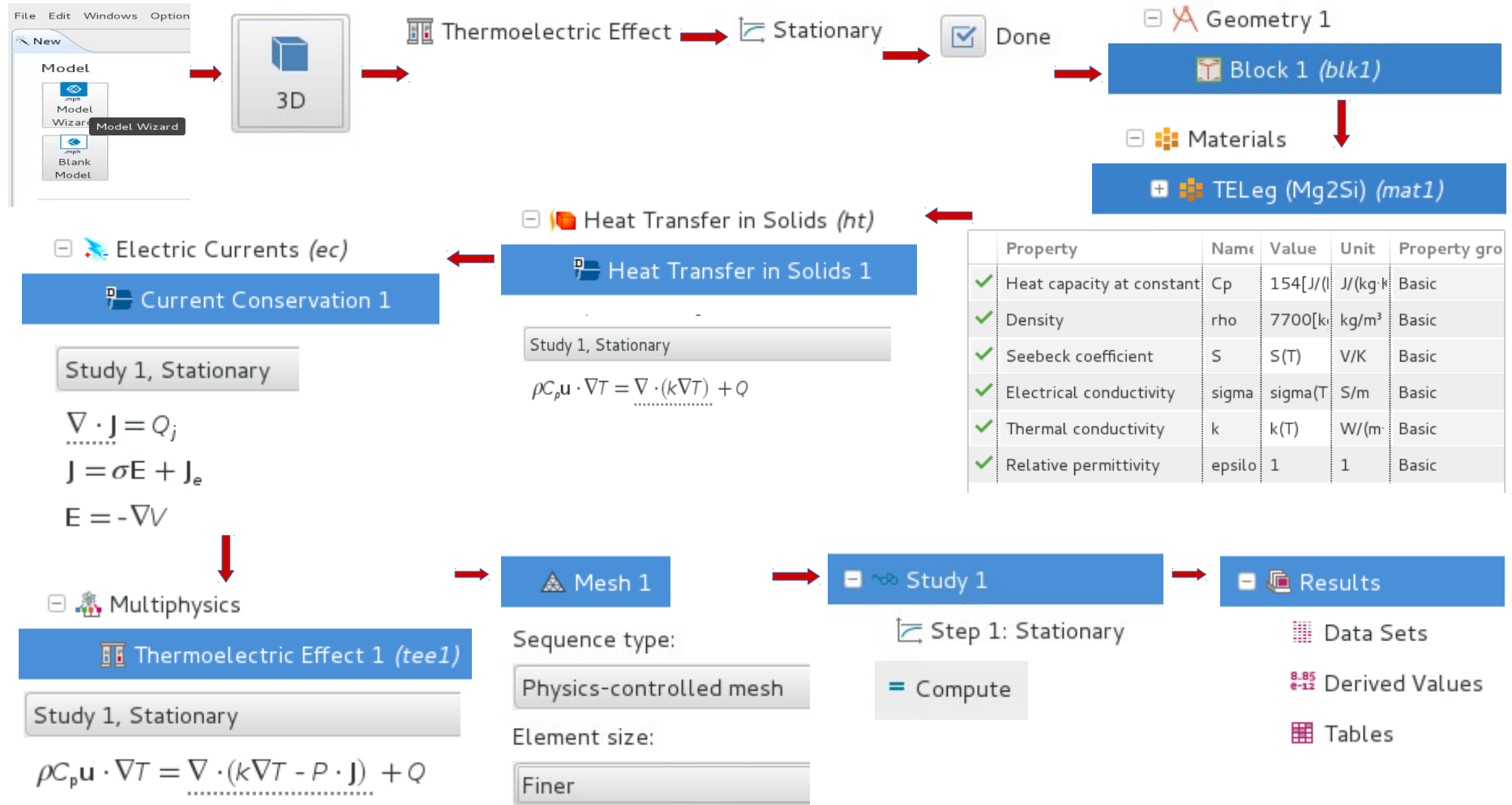
- H. Ihou-Mouko et. al., Thermoelectric Properties and Electronic Structure of p-type Mg₂Si and Mg₂Si_{0.6}Ge_{0.4} Compounds Doped with Ga, Journal of Alloys and Compounds, 509 (2011) 6503–6508.
- W. Liu et. al., Convergence of Conduction Bands as a Means of Enhancing Thermoelectric Performance of n-Type Mg₂Si_{1-x}Sn_x Solid Solutions, Physical Review Letters, 108 (2012) 166601.



Simulation in COMSOL

Marked Hidden

• STEPS

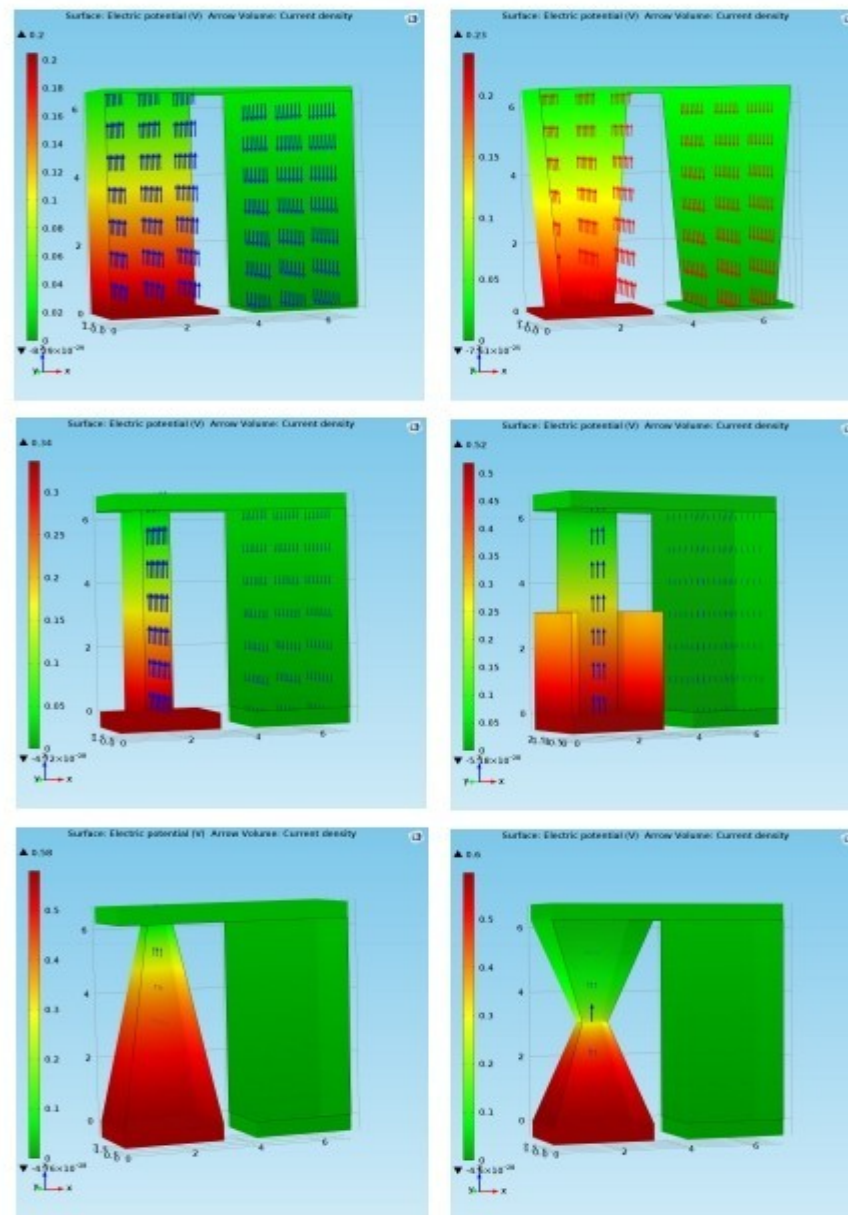
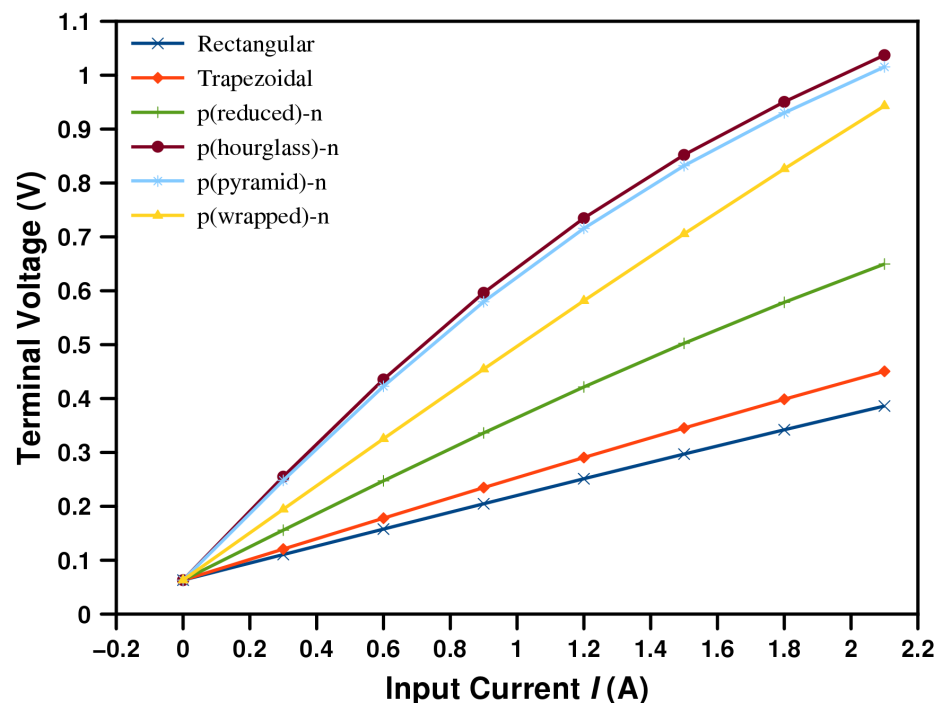


• COMSOL Multiphysics 5.1

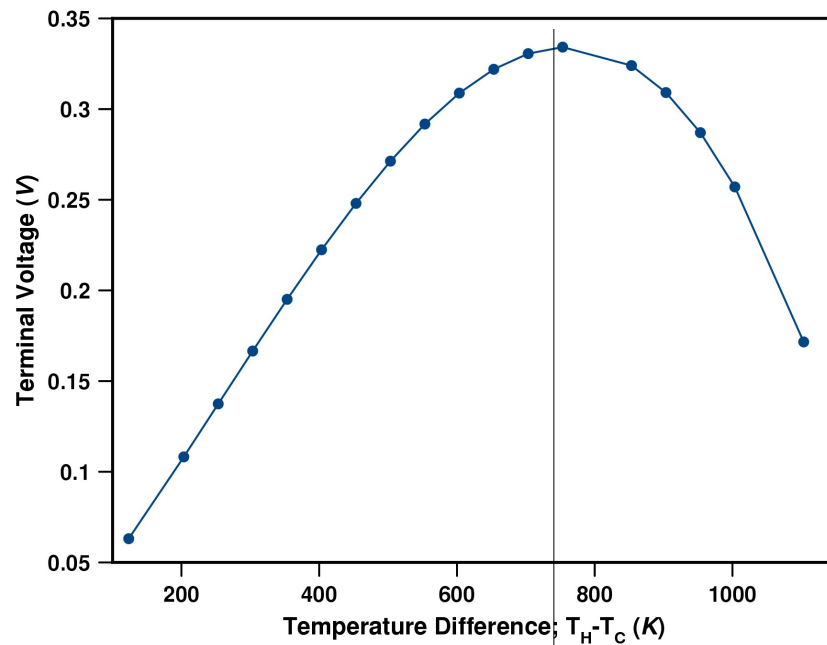


Results

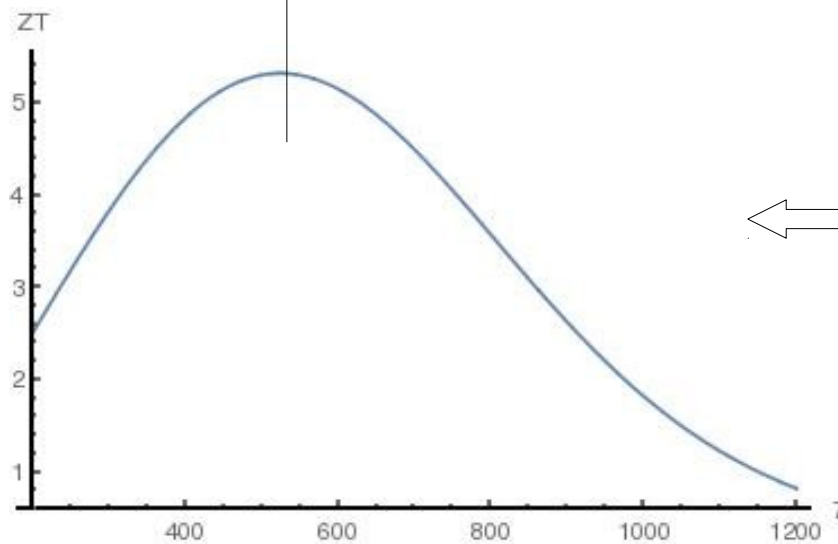
Voltage vs. Current



Results



← Voltage vs. Temperature

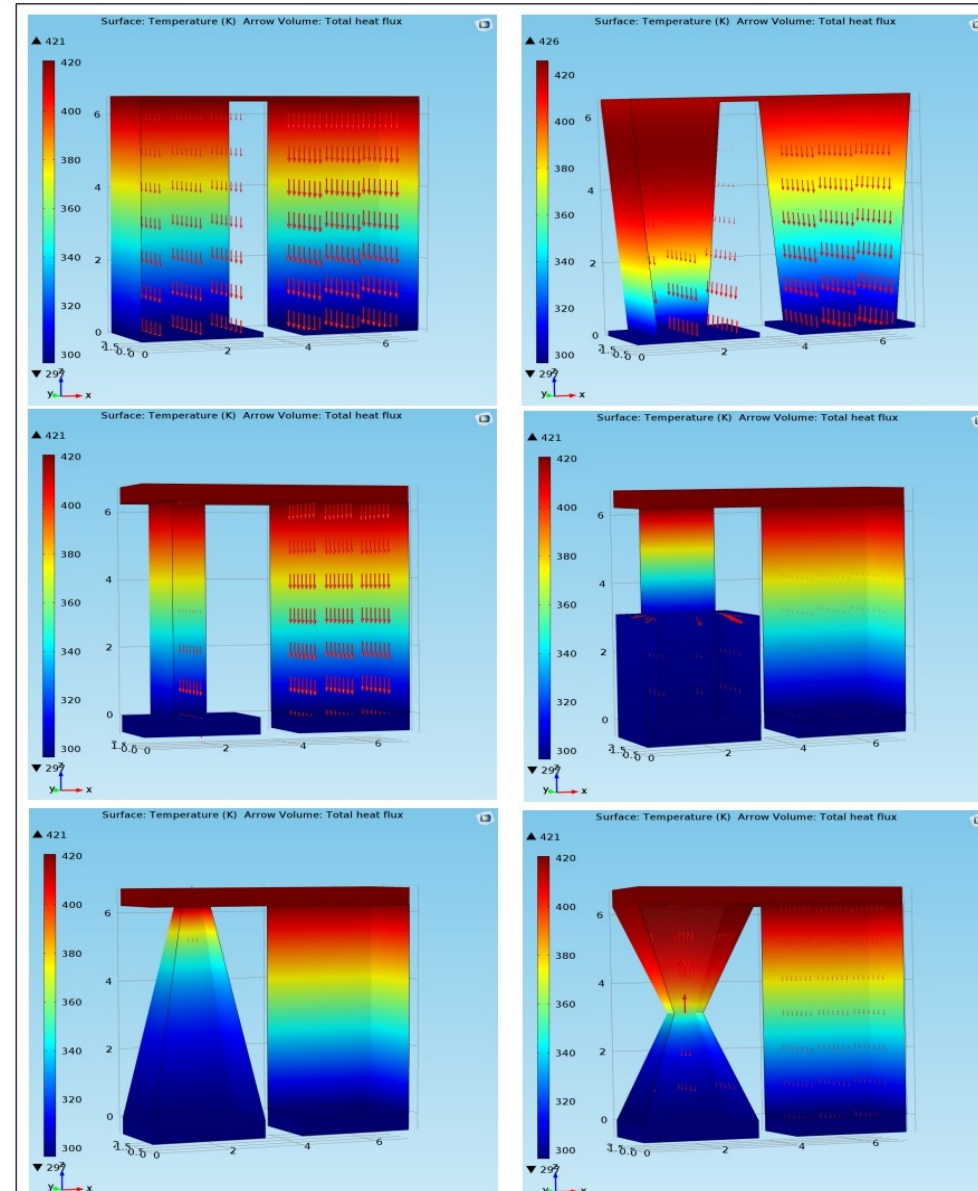
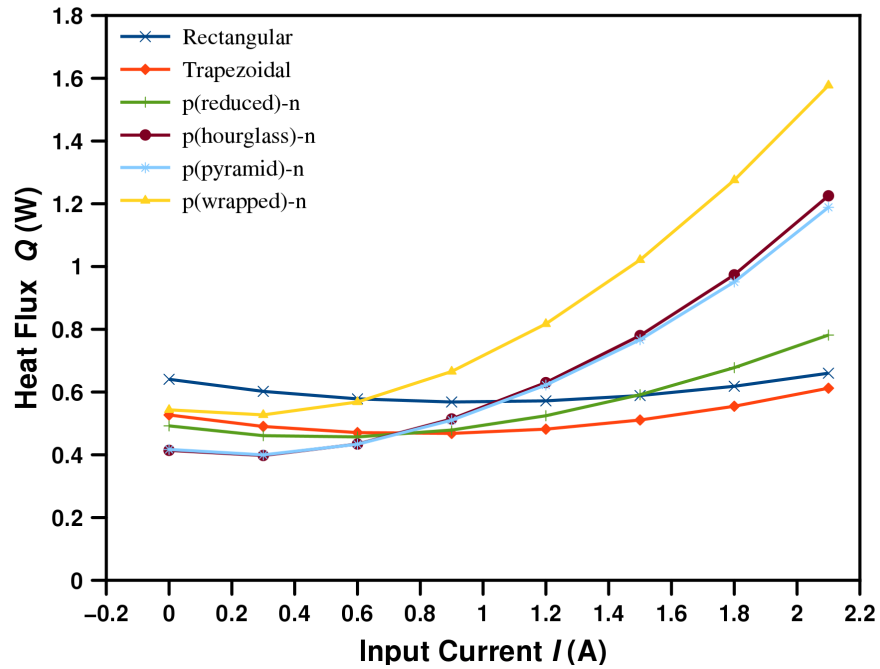


← ZT vs. Temperature



Results

- Heat flux vs. Current



- H. Julian Goldsmid, Introduction to Thermoelectricity, 1-5, Springer Series in Materials Science (2009)
- Ahmet Z. Sahin et al., The Thermoelectric as Thermoelectric Power Generator: Effect of Leg Geometry on the Efficiency and Power Generation, Energy Conversion and Management, 65 (2013) 26-32
- Christophe Goupil et al., Thermodynamics of Thermoelectric Phenomena and Applications, Entropy, (2011), 13, 1481-1517
- Yu Mu et al., Effect of Geometric Dimensions on Thermoelectric and Mechanical Performance for Mg₂Si-based Thermoelectric Unicouple, Materials Science in Semiconductor Processing, 17 (2014) 21-26
- COMSOL Multiphysics 5.1, Heat Transfer Module User's Guide
- H. Ihou-Mouko et. al., Thermoelectric Properties and Electronic Structure of p-type Mg₂Si and Mg₂Si_{0.6}Ge_{0.4} Compounds Doped with Ga, Journal of Alloys and Compounds, 509 (2011) 6503–6508.
- W. Liu et. al., Convergence of Conduction Bands as a Means of Enhancing Thermoelectric Performance of n-Type Mg₂Si_{1-x}Sn_x Solid Solutions, Physical Review Letters, 108 (2012) 166601.



Thanking You!

